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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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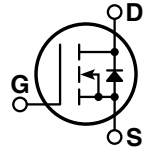
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



### Super Junction MOSFET



- Ultra low  $R_{DS(ON)}$
- Ultra Low Gate Charge,  $Q_g$
- Popular SOT-227 Package
- Low Miller Capacitance
- Avalanche Energy Rated
- N-Channel Enhancement Mode



Unless stated otherwise, Microsemi discrete MOSFETs contain a single MOSFET die. This device is made with two parallel MOSFET die. It is intended for switch-mode operation. It is not suitable for linear mode operation.

#### MAXIMUM RATINGS

All Ratings:  $T_C = 25^\circ\text{C}$  unless otherwise specified.

Symbol	Parameter	APT31N80JC3	UNIT
$V_{DSS}$	Drain-Source Voltage	800	Volts
$I_D$	Continuous Drain Current @ $T_C = 25^\circ\text{C}$	31	Amps
$I_{DM}$	Pulsed Drain Current <sup>①</sup>	93	
$V_{GS}$	Gate-Source Voltage Continuous	$\pm 20$	Volts
$V_{GSM}$	Gate-Source Voltage Transient	$\pm 30$	
$P_D$	Total Power Dissipation @ $T_C = 25^\circ\text{C}$	833	Watts
	Linear Derating Factor	6.67	W/ $^\circ\text{C}$
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to 150	$^\circ\text{C}$
$T_L$	Lead Temperature: 0.063" from Case for 10 Sec.	300	
$dv/dt$	Drain-Source Voltage slope ( $V_{DS} = 640\text{V}$ , $I_D = 31\text{A}$ , $T_J = 125^\circ\text{C}$ )	50	V/ns
$I_{AR}$	Repetitive Avalanche Current <sup>⑦</sup>	17	Amps
$E_{AR}$	Repetitive Avalanche Energy <sup>⑦</sup>	0.5	mJ
$E_{AS}$	Single Pulse Avalanche Energy <sup>④</sup>	670	

#### STATIC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
$BV_{DSS}$	Drain-Source Breakdown Voltage ( $V_{GS} = 0\text{V}$ , $I_D = 500\mu\text{A}$ )	800			Volts
$R_{DS(on)}$	Drain-Source On-State Resistance <sup>②</sup> ( $V_{GS} = 10\text{V}$ , $I_D = 22\text{A}$ )		0.125	0.145	Ohms
$I_{DSS}$	Zero Gate Voltage Drain Current ( $V_{DS} = 800\text{V}$ , $V_{GS} = 0\text{V}$ )		0.5	25	$\mu\text{A}$
	Zero Gate Voltage Drain Current ( $V_{DS} = 800\text{V}$ , $V_{GS} = 0\text{V}$ , $T_J = 150^\circ\text{C}$ )			250	
$I_{GSS}$	Gate-Source Leakage Current ( $V_{GS} = \pm 20\text{V}$ , $V_{DS} = 0\text{V}$ )			$\pm 200$	nA
$V_{GS(th)}$	Gate Threshold Voltage ( $V_{DS} = V_{GS}$ , $I_D = 2\text{mA}$ )	2.10	3	3.9	Volts

 **CAUTION:** These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

Microsemi Website - <http://www.microsemi.com>

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### DYNAMIC CHARACTERISTICS

APT31N80JC3

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
$C_{iss}$	Input Capacitance	$V_{GS} = 0V$ $V_{DS} = 25V$ $f = 1\text{ MHz}$		4510		pF
$C_{oss}$	Output Capacitance			2050		
$C_{rss}$	Reverse Transfer Capacitance			110		
$Q_g$	Total Gate Charge ③	$V_{GS} = 10V$ $V_{DD} = 400V$ $I_D = 31A @ 25^\circ C$		180	355	nC
$Q_{gs}$	Gate-Source Charge			22		
$Q_{gd}$	Gate-Drain ("Miller") Charge			90		
$t_{d(on)}$	Turn-on Delay Time	<b>RESISTIVE SWITCHING</b> $V_{GS} = 10V$ $V_{DD} = 400V$ $I_D = 31A @ 125^\circ C$ $R_G = 2.5\Omega$		25		ns
$t_r$	Rise Time			15		
$t_{d(off)}$	Turn-off Delay Time			70	80	
$t_f$	Fall Time			6	9	
$E_{on}$	Turn-on Switching Energy ⑥	<b>INDUCTIVE SWITCHING @ 25^\circ C</b> $V_{DD} = 533V, V_{GS} = 15V$ $I_D = 31A, R_G = 5\Omega$		615		$\mu J$
$E_{off}$	Turn-off Switching Energy			530		
$E_{on}$	Turn-on Switching Energy ⑥	<b>INDUCTIVE SWITCHING @ 125^\circ C</b> $V_{DD} = 533V, V_{GS} = 15V$ $I_D = 31A, R_G = 5\Omega$		1025		
$E_{off}$	Turn-off Switching Energy			580		

### SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
$I_S$	Continuous Source Current (Body Diode)			31	Amps
$I_{SM}$	Pulsed Source Current ① (Body Diode)			93	Amps
$V_{SD}$	Diode Forward Voltage ② ( $V_{GS} = 0V, I_S = -31A$ )		1	1.2	Volts
$t_{rr}$	Reverse Recovery Time ( $I_S = -31A, di_S/dt = 100A/\mu s, V_R = 400V$ )		855		ns
$Q_{rr}$	Reverse Recovery Charge ( $I_S = -31A, di_S/dt = 100A/\mu s, V_R = 400V$ )		30		$\mu C$
$dv/dt$	Peak Diode Recovery $dv/dt$ ⑤			6	V/ns

### THERMAL CHARACTERISTICS

Symbol	Characteristic	MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction to Case			0.37	$^\circ C/W$
$R_{\theta JA}$	Junction to Ambient			62	$^\circ C/W$

① Repetitive Rating: Pulse width limited by maximum junction temperature

② Pulse Test: Pulse width < 380  $\mu s$ , Duty Cycle < 2%

③ See MIL-STD-750 Method 3471

④ Starting  $T_j = +25^\circ C$ ,  $L = 115.92mH$ ,  $R_G = 25\Omega$ , Peak  $I_L = 3.4A$

⑤  $I_S = -31A$   $di_S/dt = 100A/\mu s$   $v_R = 480V$   $T_j = 125^\circ C$

⑥ Eon includes diode reverse recovery. See figures 18, 20.

⑦ Repetitive avalanche causes additional power losses that can be calculated as  $P_{AV} = E_{AR} \cdot f$

Microsemi reserves the right to change, without notice, the specifications and information contained herein.

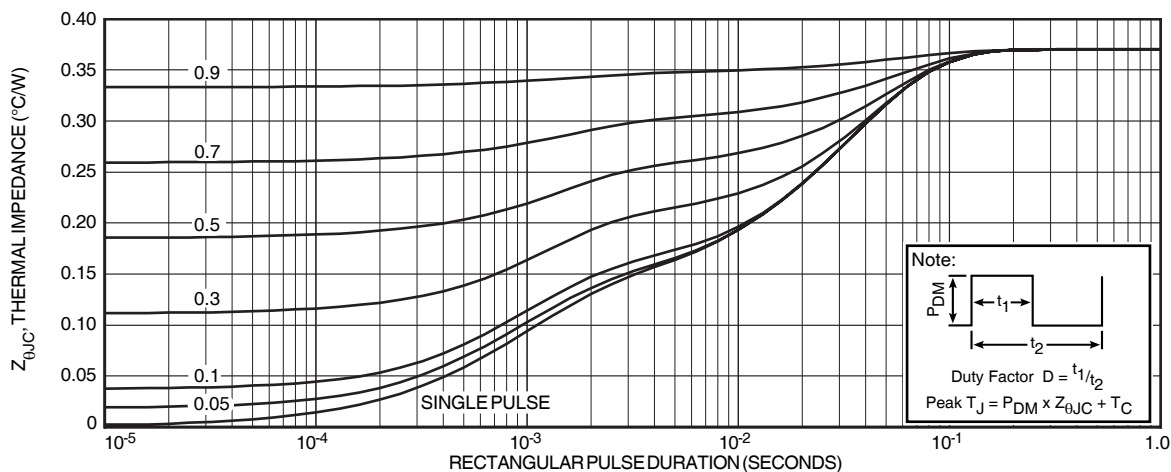


FIGURE 1, MAXIMUM EFFECTIVE TRANSIENT THERMAL IMPEDANCE, JUNCTION-TO-CASE vs PULSE DURATION

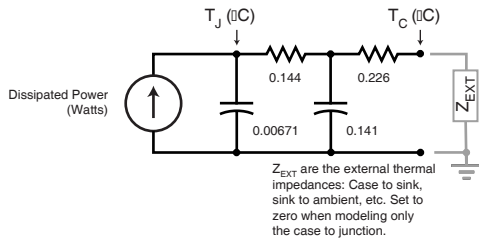


FIGURE 2, TRANSIENT THERMAL IMPEDANCE MODEL

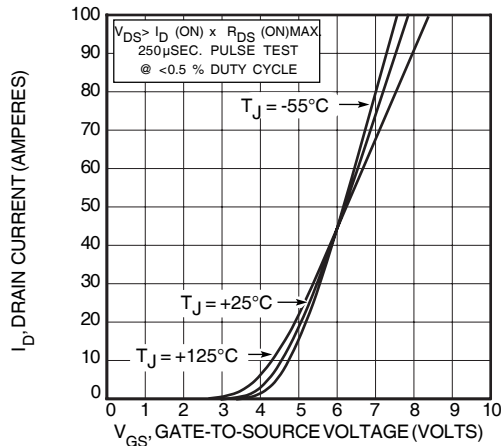


FIGURE 4, TRANSFER CHARACTERISTICS

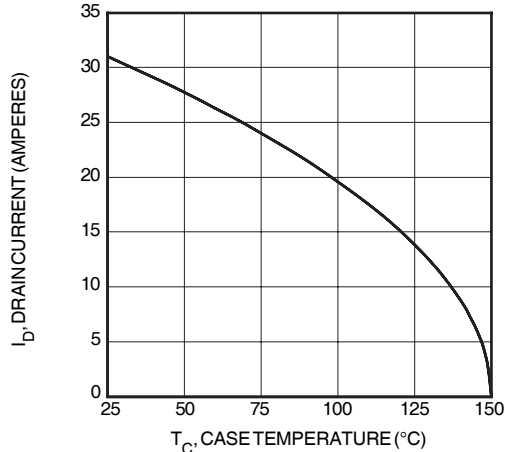


FIGURE 6, MAXIMUM DRAIN CURRENT vs. CASE TEMPERATURE

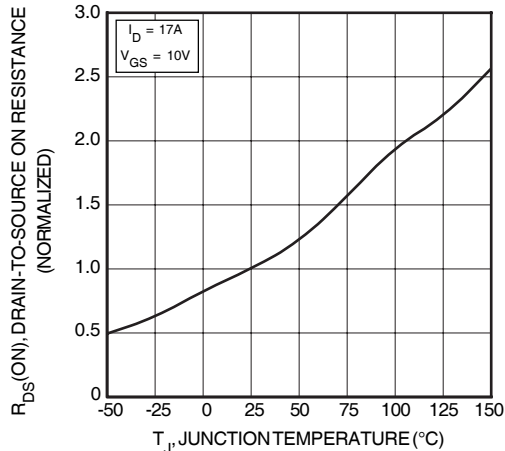


FIGURE 8, ON-RESISTANCE vs. TEMPERATURE

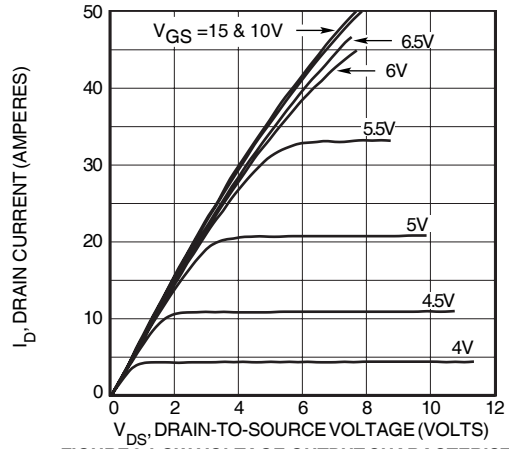


FIGURE 3, LOW VOLTAGE OUTPUT CHARACTERISTICS

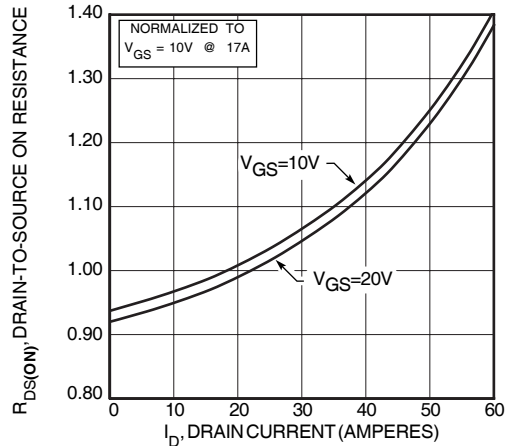


FIGURE 5,  $R_{DS(ON)}$  vs. DRAIN CURRENT

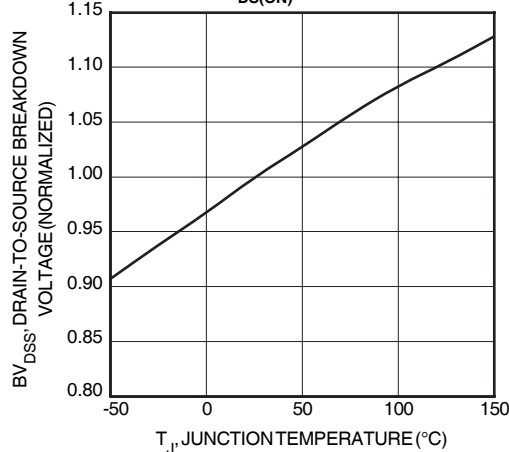


FIGURE 7, BREAKDOWN VOLTAGE vs. TEMPERATURE

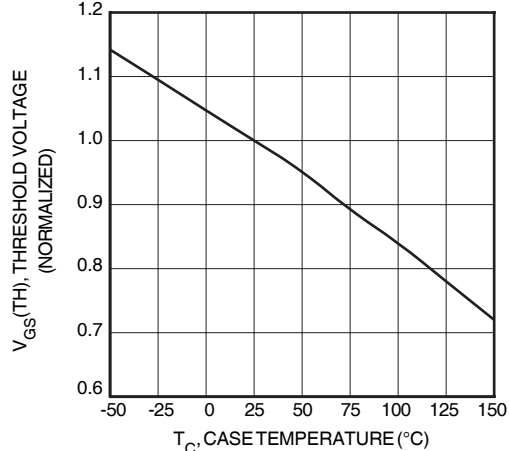
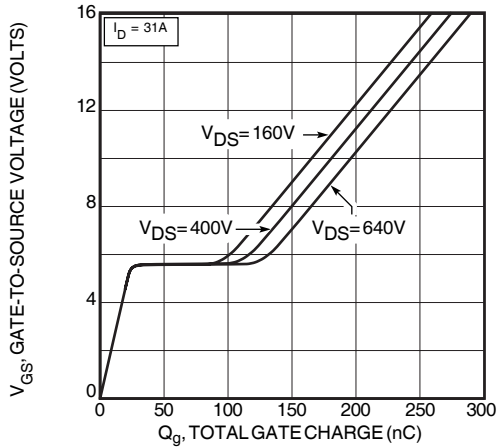


FIGURE 9, THRESHOLD VOLTAGE vs. TEMPERATURE

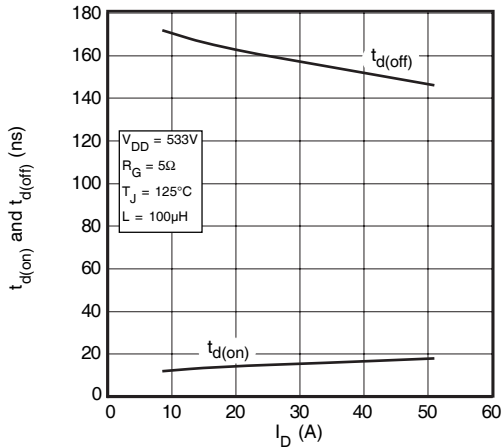
$I_D$ , DRAIN CURRENT (AMPERES)

Graph removed

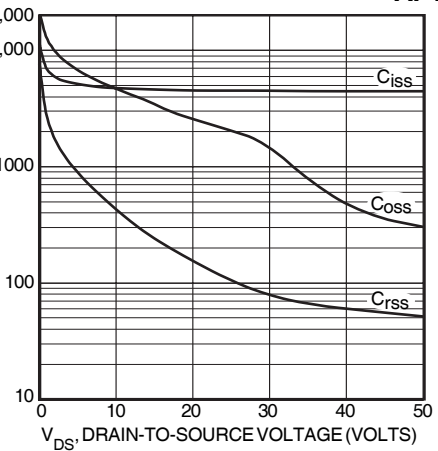
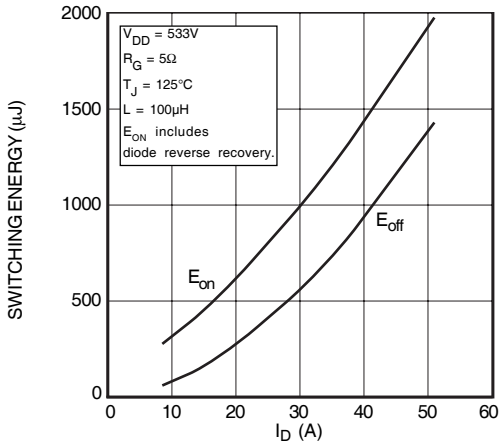
$V_{DS}$ , DRAIN-TO-SOURCE VOLTAGE (VOLTS)  
**FIGURE 10, MAXIMUM SAFE OPERATING AREA**



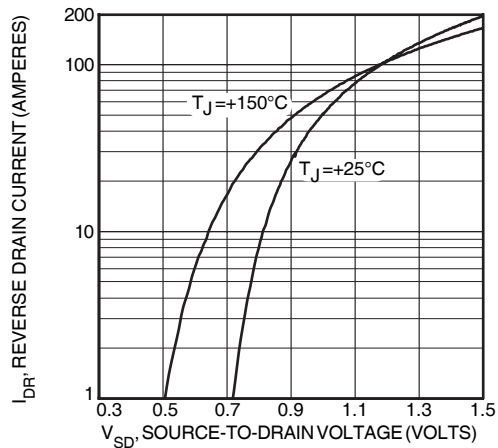
**FIGURE 12, GATE CHARGES vs GATE-TO-SOURCE VOLTAGE**



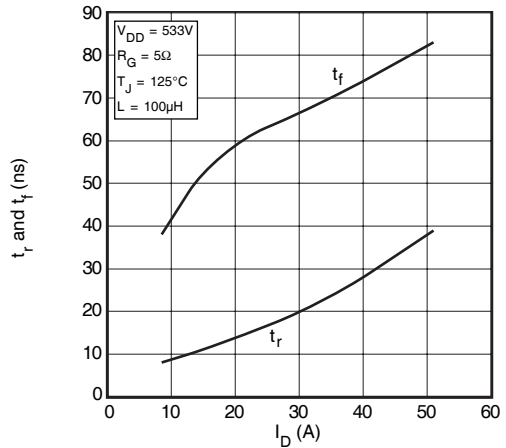
**FIGURE 14, DELAY TIMES vs CURRENT**



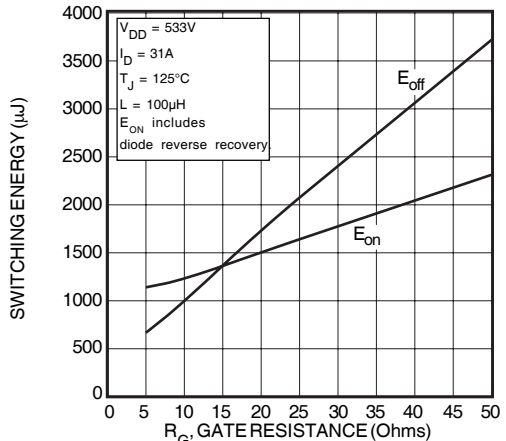
**FIGURE 11, CAPACITANCE vs DRAIN-TO-SOURCE VOLTAGE**



**FIGURE 13, SOURCE-DRAIN DIODE FORWARD VOLTAGE**



**FIGURE 15, RISE AND FALL TIMES vs CURRENT**



**FIGURE 17, SWITCHING ENERGY VS. GATE RESISTANCE**

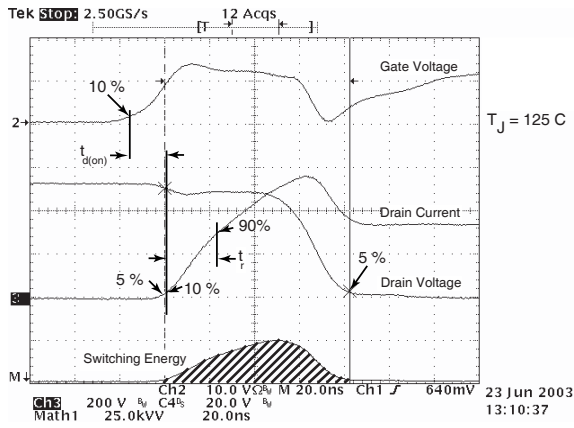


Figure 18, Turn-on Switching Waveforms and Definitions

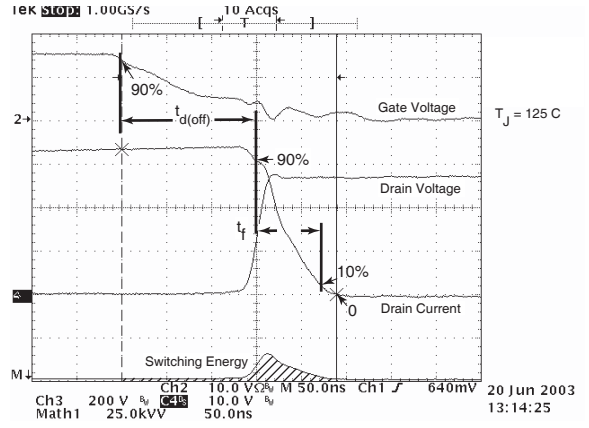


Figure 19, Turn-off Switching Waveforms and Definitions

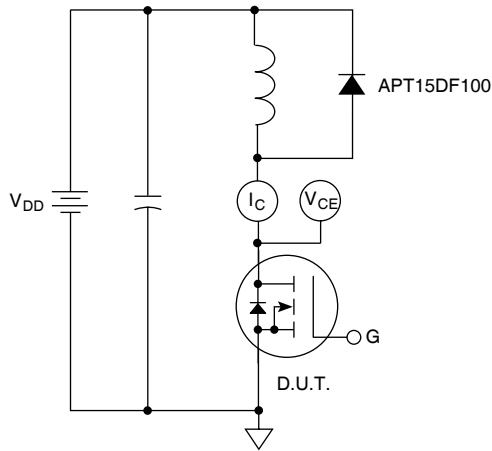
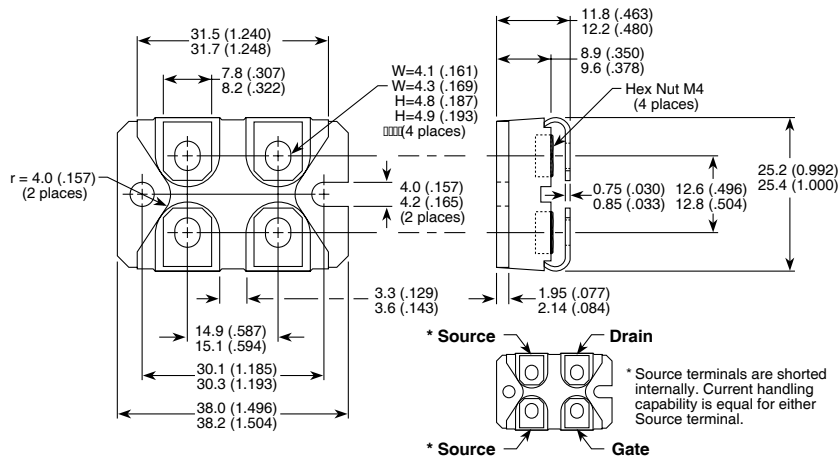


Figure 20, Inductive Switching Test Circuit

SOT-227 (ISOTOP®) Package Outline



Dimensions in Millimeters and (Inches)

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